

Acknowledgments

The *ASEAN+3 Bond Market Guide 2016: Hong Kong, China* was published in November 2016.¹ Being a mature market, the main features and functions in the bond market in Hong Kong, China have largely remained consistent in the years since publication, which means that a complete review is not required just yet. At the same time, an update on a number of recent market developments, particularly those that mirror or touch on developments in other jurisdictions, such as Bond Connect, is necessary.

As such, this update was compiled to coincide with the publication of the *The Inter-Bank Bond Market in the People's Republic of China: An ASEAN+3 Bond Market Guide* in August 2020.

In addition to a description of Bond Connect features in the Hong Kong bond market, this update contains information on the Government Green Bond Programme, the Green Bond Grant Scheme, the Pilot Bond Grant Scheme, a revision of the Professional Investor Rules, as well as additions to eligible collateral for the RMB Liquidity Facility offered by the Hong Kong Monetary Authority.

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No part of this update represents the official views or opinions of any institution that participated in this activity as an ABMF member, observer, or expert. The ABMF Sub-Forum 1 team bears sole responsibility for the contents of this update.

This update and those relating to other ASEAN+3 bond markets are available for download from *AsianBondsOnline*.²

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¹ See https://asianbondsonline.adb.org/documents/abmf_hkg_bond_market_guide_2016.pdf.

² See <https://asianbondsonline.adb.org>.